Product Change Notification - KSRA-20EIEO658

Date: 13 Jul 2017

Product Category: 16-Bit - Microcontrollers and Digital Signal Controllers

Notification subject: CCB 2978 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 0.25um TSMC wafer technology available in 28L QFN-S package at NSEB assembly site

Notification text:

PCN Status:
Initial notification

Microchip Parts Affected:
Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:
Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.25um TSMC wafer technology available in 28L QFN-S package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T or 8600 die attach and G770HCD or G700LTD mold compound material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	NSEB Assembly Site		NSEB Assembly Site
Wire material	Au Wire		CuPdAu Wire
Die attach material	8200T	8600	8600
Molding compound material	G770HCD	G700LTD	G700LTD
Lead frame material	C194		C194

Impacts to Data Sheet:
None

Change Impact:
None

Reason for Change:
To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:
In Progress

Estimated Qualification Completion Date:

December 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	July 2017						-->	December 2017				
Workweek	26	27	28	29	30	31		49	50	51	52	53
Initial PCN Issue Date			X									
Qual Report Availability											X	
Final PCN Issue Date											X	

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:
July 13, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN_KSRA-20EIEO658_Affected CPN.pdf
PCN_KSRA-20EIEO658_Qual Plan.pdf
PCN_KSRA-20EIEO658_Affected CPN.xlsx

Please contact your local Microchip sales office with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

PCN_ KSRA-20EIEO658
CATALOG_PART_NBR
DSPIC33FJ06GS102A-E/MM
DSPIC33FJ06GS102A-I/MM
DSPIC33FJ06GS102AT-E/MM
DSPIC33FJ06GS102AT-I/MM
DSPIC33FJ06GS102-E/MM
DSPIC33FJ06GS102-I/MM
DSPIC33FJ06GS102T-E/MM
DSPIC33FJ06GS102T-I/MM
DSPIC33FJ06GS202A-E/MM
DSPIC33FJ06GS202A-I/MM
DSPIC33FJ06GS202AT-E/MM
DSPIC33FJ06GS202AT-I/MM
DSPIC33FJ06GS202-E/MM
DSPIC33FJ06GS202-E/MMC04
DSPIC33FJ06GS202-I/MM
DSPIC33FJ06GS202T-E/MM
DSPIC33FJ06GS202T-E/MMC04
DSPIC33FJ06GS202T-E/MMC06
DSPIC33FJ06GS202T-I/MM
DSPIC33FJ09GS302-E/MM
DSPIC33FJ09GS302-I/MM
DSPIC33FJ09GS302T-E/MM
DSPIC33FJ09GS302T-I/MM
DSPIC33FJ128GP202-E/MM
DSPIC33FJ128GP202-I/MM
DSPIC33FJ128GP202T-E/MM
DSPIC33FJ128GP202T-I/MM
DSPIC33FJ128GP802-E/MM
DSPIC33FJ128GP802-I/MM
DSPIC33FJ128GP802T-E/MM
DSPIC33FJ128GP802T-I/MM
DSPIC33FJ128GP802T-I/MM038
DSPIC33FJ128GP802T-I/MM039
DSPIC33FJ128MC202-E/MM
DSPIC33FJ128MC202-I/MM
DSPIC33FJ128MC202T-E/MM
DSPIC33FJ128MC202T-I/MM
DSPIC33FJ128MC802-E/MM
DSPIC33FJ128MC802-H/MM
DSPIC33FJ128MC802-I/MM
DSPIC33FJ128MC802T-E/MM
DSPIC33FJ128MC802T-H/MM
DSPIC33FJ128MC802T-I/MM

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CATALOG_PART_NBR
DSPIC33FJ16GS402-50I/MM
DSPIC33FJ16GS402-E/MM
DSPIC33FJ16GS402-H/MM
DSPIC33FJ16GS402-I/MM
DSPIC33FJ16GS402T-50I/MM
DSPIC33FJ16GS402T-E/MM
DSPIC33FJ16GS402T-H/MM
DSPIC33FJ16GS402T-I/MM
DSPIC33FJ16GS502-50I/MM
DSPIC33FJ16GS502-E/MM
DSPIC33FJ16GS502-E/MMC03
DSPIC33FJ16GS502-H/MM
DSPIC33FJ16GS502-I/MM
DSPIC33FJ16GS502T-50I/MM
DSPIC33FJ16GS502T-E/MM
DSPIC33FJ16GS502T-E/MMC03
DSPIC33FJ16GS502T-H/MM
DSPIC33FJ16GS502T-I/MM
DSPIC33FJ32GP202-E/MM
DSPIC33FJ32GP202-I/MM
DSPIC33FJ32GP202T-E/MM
DSPIC33FJ32GP202T-I/MM
DSPIC33FJ32GP302-E/MM
DSPIC33FJ32GP302-I/MM
DSPIC33FJ32GP302T-E/MM
DSPIC33FJ32GP302T-E/MMC03
DSPIC33FJ32GP302T-I/MM
DSPIC33FJ32MC202-E/MM
DSPIC33FJ32MC202-H/MM
DSPIC33FJ32MC202-I/MM
DSPIC33FJ32MC202T-E/MM
DSPIC33FJ32MC202T-H/MM
DSPIC33FJ32MC202T-I/MM
DSPIC33FJ32MC302-E/MM
DSPIC33FJ32MC302-I/MM
DSPIC33FJ32MC302T-E/MM
DSPIC33FJ32MC302T-I/MM
DSPIC33FJ64GP202-E/MM
DSPIC33FJ64GP202-I/MM
DSPIC33FJ64GP202T-E/MM
DSPIC33FJ64GP202T-I/MM
DSPIC33FJ64GP802-E/MM
DSPIC33FJ64GP802-H/MM

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PCN_ KSRA-20EIEO658
CATALOG_PART_NBR
DSPIC33FJ64GP802-I/MM
DSPIC33FJ64GP802-I/MMB21
DSPIC33FJ64GP802T-E/MM
DSPIC33FJ64GP802T-E/MM032
DSPIC33FJ64GP802T-E/MM041
DSPIC33FJ64GP802T-H/MM
DSPIC33FJ64GP802T-I/MM
DSPIC33FJ64GP802T-I/MMB21
DSPIC33FJ64MC202-E/MM
DSPIC33FJ64MC202-E/MMC04
DSPIC33FJ64MC202-I/MM
DSPIC33FJ64MC202-I/MM030
DSPIC33FJ64MC202-I/MMC21
DSPIC33FJ64MC202T-E/MM
DSPIC33FJ64MC202T-E/MMC04
DSPIC33FJ64MC202T-I/MM
DSPIC33FJ64MC202T-I/MM030
DSPIC33FJ64MC202T-I/MMC21
DSPIC33FJ64MC802-E/MM
DSPIC33FJ64MC802-H/MM
DSPIC33FJ64MC802-I/MM
DSPIC33FJ64MC802T-E/MM
DSPIC33FJ64MC802T-H/MM
DSPIC33FJ64MC802T-I/MM
HA7612-I/MM033
HA7612-I/MM036
HA7612T-I/MM033
HA7612T-I/MM036
PIC24HJ128GP202-E/MM
PIC24HJ128GP202-I/MM
PIC24HJ128GP202T-E/MM
PIC24HJ128GP202T-I/MM
PIC24HJ128GP502-E/MM
PIC24HJ128GP502-H/MM
PIC24HJ128GP502-I/MM
PIC24HJ128GP502T-E/MM
PIC24HJ128GP502T-H/MM
PIC24HJ128GP502T-I/MM
PIC24HJ32GP202-E/MM
PIC24HJ32GP202-H/MM
PIC24HJ32GP202-I/MM
PIC24HJ32GP202T-I/MM
PIC24HJ32GP302-E/MM

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CATALOG_PART_NBR
PIC24HJ32GP302-I/MM
PIC24HJ32GP302T-E/MM
PIC24HJ32GP302T-I/MM
PIC24HJ64GP202-E/MM
PIC24HJ64GP202-I/MM
PIC24HJ64GP202T-E/MM
PIC24HJ64GP202T-I/MM
PIC24HJ64GP502-E/MM
PIC24HJ64GP502-H/MM
PIC24HJ64GP502-I/MM
PIC24HJ64GP502T-E/MM
PIC24HJ64GP502T-H/MM
PIC24HJ64GP502T-I/MM